METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

ABSTRACT

A method of manufacturing a semiconductor device of the present invention includes a coating process in which a pasty thermosetting resin composition having a flux activity is coated on at least either one of a substrate and a semiconductor chip; a bonding process in which the substrate and the semiconductor chip are electrically bonded while placing the pasty thermosetting resin composition in between; a curing process in which the pasty thermosetting resin composition is cured under heating; and a cooling process, succeeding to the curing process, in which cooling is performed at a cooling rate between 10 [°C/hour] or above and 50 [°C/hour] or below.

FIG. 1